

400mW SOD-123 SURFACE MOUNT Small Outline Gull Wing Lead Plastic Package High Voltage & High Conductance Fast Switching Diode

Green Product

Absolute Maximum Ratings T_A = 25°C unless otherwise noted

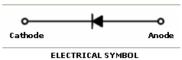
Symbol	Parameter	Value	Units	
P _D	Power Dissipation	400	mW	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TJ	T _J Operating Junction Temperature +150		°C	
V _{RRM}	Repetitive Peak Reverse Voltage	250	V	
I _{F(AV)}	Average Rectified Forward Current	200	mA	

These ratings are limiting values above which the serviceability of the diode may be impaired.

SOD-123 Gull Wing Lead

Specification Features:

- Fast Switching Diode
- General Purpose Diodes High Voltage Application Diodes
- Gull Wing Lead SOD-123 Small Outline Plastic Package
- Surface Device Type Mounting
- RoHS Compliant
- Green EMC
- Matte Tin(Sn) Lead Finish
- Band Indicates Cathode
- Weight: approx. 0.01g



DEVICE MARKING CODE:

Device Type		Device Marking	
	BAV19WG	A8	
	BAV20WG	T2	
	BAV21WG	Т3	

Electrical Characteristics $T_A = 25$ °C unless otherwise noted

Cumbal	Parameter		Test Condition	Limits		l lmit
Symbol	Parameter		rest Condition	Min	Max	Unit
Ву	Breakdown Voltage	BAV19WG	I _R =100μA	120		Volts
		BAV20WG		200		Volts
		BAV21WG		250		Volts
I _R	Reverse Leakage Current	BAV19WG	V _R =100V		100	nA
		BAV20WG	V _R =150V		100	nA
		BAV21WG	V _R =200V		100	nA
V _F	Forward Voltage		I _F =100mA		1.0	Volts
			I _F =200mA		1.25	Volts
T _{RR}	Reverse Recovery Time		I _F =I _R =30mA			
			R _L =100Ω		50	nS
			I _{RR} =3mA			
С	Capacitance		V _R =0V, f=1M _{HZ}		5.0	pF

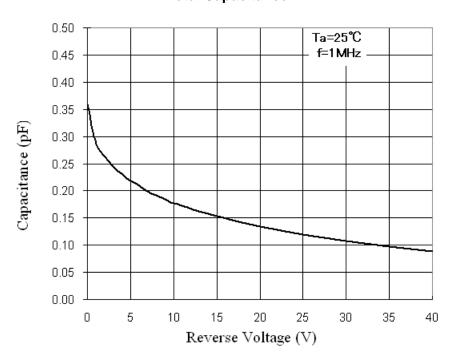
Number: DB-282

May 2017 Release, Revision A

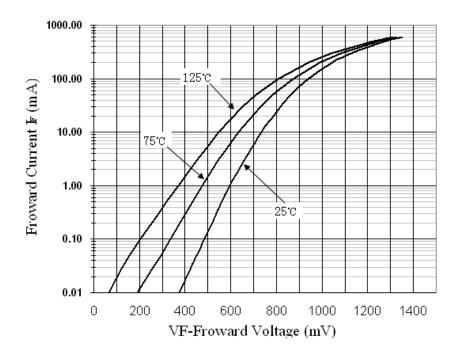


Typical Performance Characteristics

Total Capacitance



Forward Voltage vs Ambient Temperature

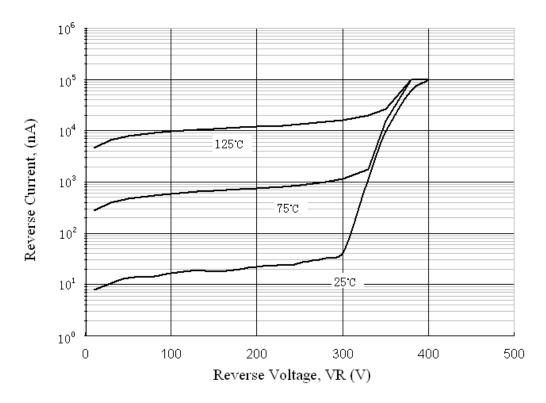


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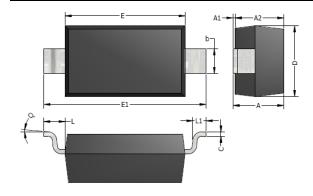
Reverse Current vs Reverse VoltageReverse



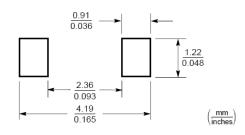




SOD123 Gull Wing Lead Package Outline



Typical Soldering Pattern:



DIM	MILLIMETERS		INCHES		
	MIN	MAX	MIN	MAX	
Α	1.05	1.25	0.041	0.049	
A1	0.00	0.10	0.000	0.004	
A2	1.05	1.15	0.041	0.045	
b	0.50	0.70	0.020	0.028	
С	0.08	0.15	0.003	0.006	
D	1.50	1.70	0.059	0.067	
Е	2.60	2.80	0.102	0.110	
E1	3.55	3.85	0.140	0.152	
L	0.50 REF.		0.020 REF.		
L1	0.25	0.45	0.010	0.018	
θ	0 °	8°	O °	8 °	

Note:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.





NOTICE

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Tak Cheong Semiconductor Co., Ltd., or anyone on its behalf, assumes no responsibility or liability for any damagers resulting from such improper use of sale.

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